

UNCONTROLLED DOCUMENT

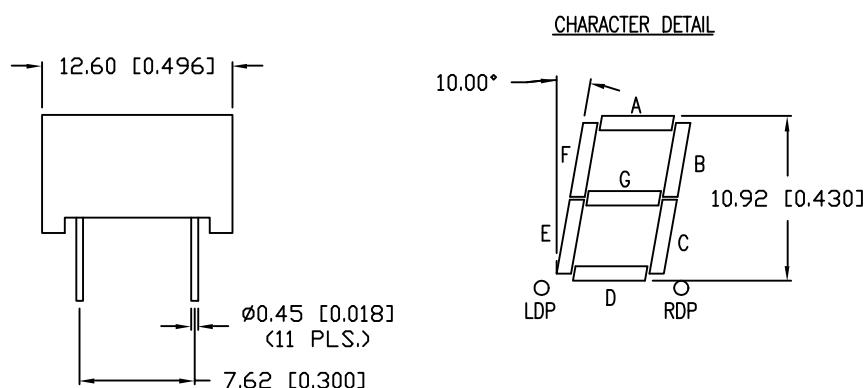
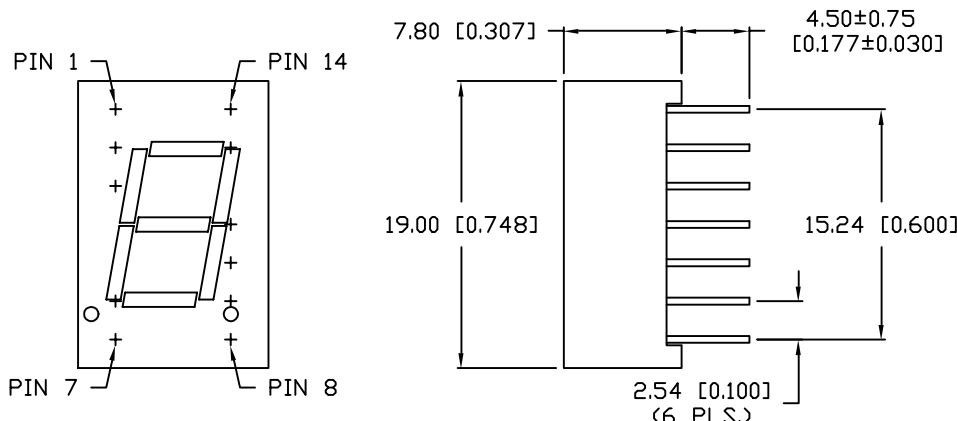
(LX)

PART NUMBER

REV.

LDS-A413BI

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
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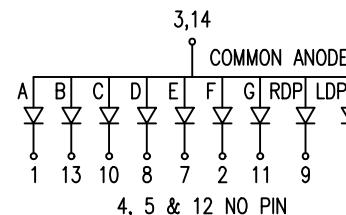
ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585		nm	
FORWARD VOLTAGE		2.1	2.5	V _f	
REVERSE VOLTAGE	5.0			V _r	
AXIAL INTENSITY		3900		μcd	$I_f=100\mu\text{A}$
EMITTED COLOR:	YELLOW				$I_f=10\text{mA}$
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY	3 SEC. MAX	

* $t < 10\mu\text{s}$



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*UNLESS OTHERWISE SPECIFIED TOLERANCE IS $\pm 0.25\text{mm}$ ($\pm 0.010''$)

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	0.43" SINGLE DIGIT, SEVEN SEGMENT DISPLAY, 585nm YELLOW CHIPS, GRAY FACE WITH WHITE SEGMENTS, COMMON ANODE.		

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			PAGE: 1 OF 1
			SCALE: N/A